

## Type BMB-S Series

### Key Features

Effective EMI Protection

Wide Frequency Characteristics

High soldering Heat Resistance

Suited to a Variety of Applications

Current Handling up to 6ADC

Terminal finish matte Sn over Cu/Ni underplate



The BMB-S Series of beads have a monolithic inorganic material construction that minimizes the effect of electromagnetic interference and are ideal for noise filtering of power line. This Series of chip beads have lower DC resistance than the BMB P Series and are more effective in power saving applications. Capable of handling currents up to 6A DC the BMB-S chip beads are designed for high current handling.

### Electrical Performance

Part Number	Impedance ( $\Omega$ ) at 100MHz	DC Resistance ( $\Omega$ ) maximum	Rated Current (mA) maximum
BMB-1J-0026S-N1	26 $\pm$ 25%	0.015	6000
BMB-1J-0030S-N1	30 $\pm$ 25%	0.01	5000
BMB-1J-0070S-N1	70 $\pm$ 25%	0.025	3000
BMB-1J-0120S-N1	120 $\pm$ 25%	0.04	3000
BMB-1J-0220S-N1	220 $\pm$ 25%	0.04	2500
BMB-1J-0330S-N1	330 $\pm$ 25%	0.085	1500

Operating temperature range - -55 ~ +125°C

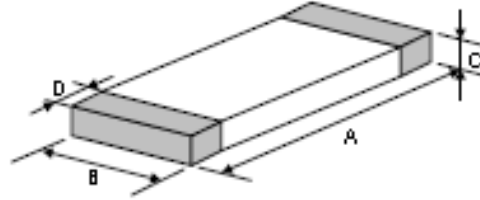
Temperature should be less than 25°C when rated current is applied.

Storage:

Temperature Range: -40 ~ +85°C

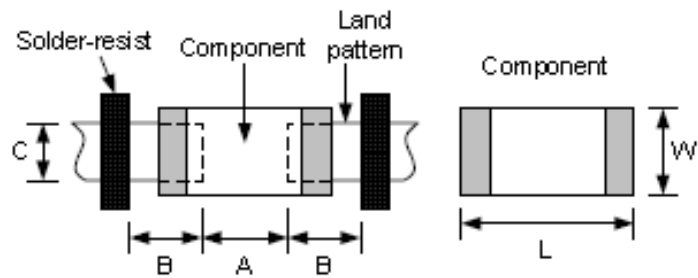
Humidity: Less than 75% RH

### Product Dimensions



Size	A (mm)	B (mm)	C (mm)	D (mm)
0603	1.6 ±0.15	0.8 ±0.15	0.8 ±0.15	0.3 ±0.20

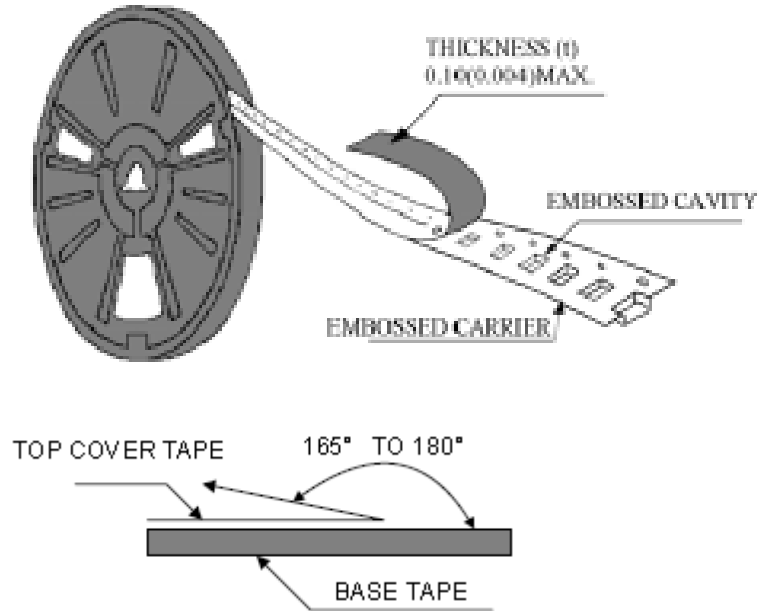
### Recommended PCB Layout



Size	0603	
Component	L	1.6
	W	0.8
A	0.6 ~ 0.8	
B	0.6 ~ 0.8	
C	0.6 ~ 0.8	

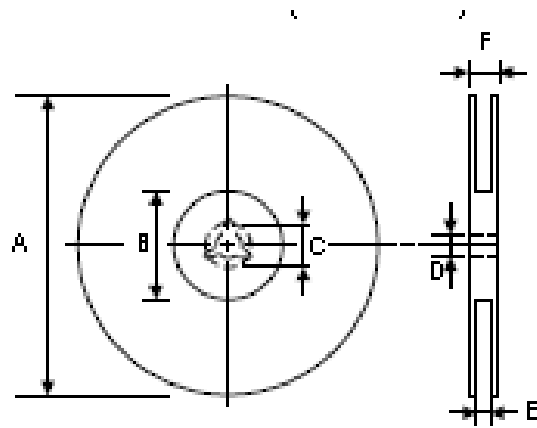
Packaging

Peel off force:

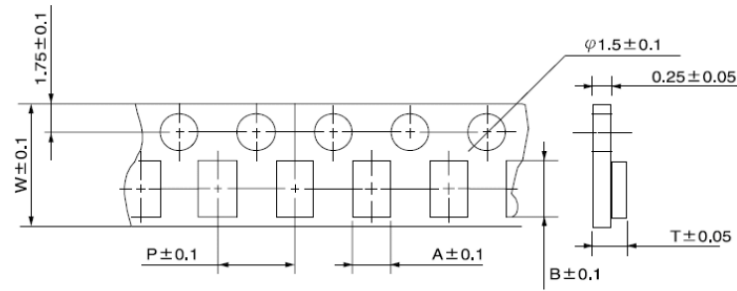


The force for peeling off cover tape is 10 grams in the direction shown

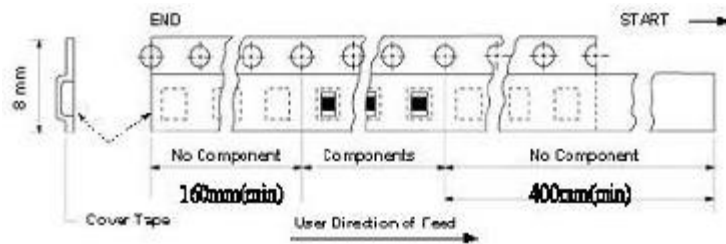
Dimensions (mm)



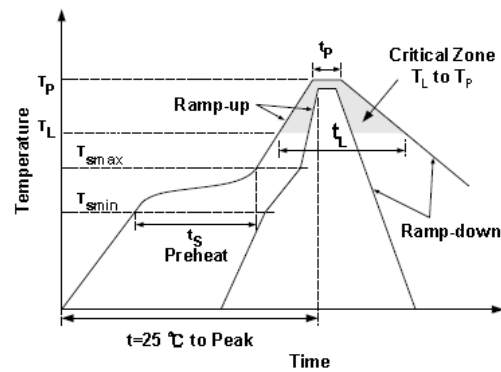
A	B	C	D	E	F
$178 \pm 1$	$60 +0.5$ $-0.1$	--	$13 \pm 0.2$	$9 \pm 0.5$	$12 \pm 0.5$



Size	A	B	W	P	T	Chips / Reel
0603	1.1	1.9	8	4	1.1	4000



## Recommended Reflow Solder Profile



Profile Feature		Pb Free
Preheat	$t_s$	60 ~ 180 seconds
	$T_{smin}$	150°C
	$T_{smax}$	200°C
Average Ramp up rate ( $T_{smax}$ to $T_p$ )		3°C/second max.
Time main above	Temperature ( $T_L$ )	217°C
	Time ( $t_L$ )	60 ~ 150 seconds
Peak Temperature ( $T_p$ )		250 ~ 260°C
Time within 5°C of actual peak temperature ( $t_p$ )		10 seconds
Ramp down rate		6°C/second max.
Time 25°C to peak temperature		8 minutes max.

Typical Characteristic Curves (T=25°C)

